| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L2 | 360 | ((DECAPSULAT$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT$4) NEAR3 (REMOV$4 OR DISSOLV$4 OR STRIP$4 OR PEEL$4 ))) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT) OR ELECTRONICS)) AND ((CHEMICAL OR SOLUTION OR FORMULATION OR SOLVENT OR ACID OR ETCHANT OR STRIPPER) NEAR8 ((HEAT OR TEMPERATURE) NEAR5 (ACTIVAT$4 OR REACT$4 OR REACTIV$4 OR SENSITIV$4))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/01 01:32 |
| L4 | 60 | DECAPSULAT$4 AND ((CHEMICAL OR SOLUTION OR FORMULATION OR SOLVENT OR ACID OR ETCHANT OR STRIPPER) NEAR8 ((HEAT OR TEMPERATURE) NEAR5 (ACTIVAT$4 OR REACT$4 OR REACTIV$4 OR SENSITIV$4))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/01 01:35 |

| L7 | 112 | ((DECAPSULAT$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT$4) NEAR3 (REMOV$4 OR DISSOLV$4 OR STRIP$4 OR PEEL$4 )) ) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT) OR ELECTRONICS)) AND ((SOLVENT OR ACID OR STRIPPER OR SOLUTION OR CHEMICAL OR FORMULATION) NEAR8 (HEATED OR HOT OR THERMAL$4 OR HEATER OR WARM$4) NEAR8 (GAS OR AIR OR NITROGEN)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/01 01:54 |
|----|-----|----|----|----|----|----|
| L10 | 639 | ((DECAPSULAT$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT$4) NEAR3 (REMOV$4 OR DISSOLV$4 OR STRIP$4 OR PEEL$4 )) ) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT) OR ELECTRONICS)) AND ((GAS OR AIR OR NITROGEN) NEAR5 (HEATED OR HOT OR THERMAL$4 OR HEATER OR WARM$4)) | USPAT; USOCR; IBM_TDB | OR | ON | 2007/04/01 03:14 |

| L17 | 120 | ((DECAPSULAT$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT$4) NEAR3 (REMOV$4 OR DISSOLV$4 OR STRIP$4 OR PEEL$4 )) ) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT) OR ELECTRONICS)) AND (((GAS OR AIR OR NITROGEN) NEAR5 (HEATED OR HOT OR THERMAL$4 OR HEATER OR WARM$4)) AND (ACID NEAR4 (SULFURIC OR NITRIC)) | USPAT; USOCR; IBM_TDB | OR | ON | 2007/04/01 03:19 |
|---|---|---|---|---|---|---|

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--------------|-----|------------------|---------|------------|
| L52 | 67 | ((DECAPSULAT$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT$4) NEAR3 (REMOV$4 OR DISSOLV$4 OR STRIP$4 OR PEEL$4 )) ) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT))) AND ((SOLVENT OR ACID OR STRIPPER OR SOLUTION OR CHEMICAL OR FORMULATION) NEAR8 (DROP OR PUDDLE OR POOL GLOBULE OR DROPLETS)) AND ((GAS OR AIR OR NITROGEN) NEAR5 (HEATED OR HOT OR THERMAL$4 OR HEATER OR WARM$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/01 00:59 |

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L50 | 216 | ((DECAPSULAT$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY) NEAR3 (REMOV$4 OR DISSOLV$4 OR STRIP$4 )) ) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT))) AND ((SOLVENT OR ACID OR STRIPPER OR SOLUTION OR CHEMICAL OR FORMULATION) NEAR8 (DROP OR PUDDLE OR POOL GLOBULE OR DROPLETS)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/04/01 00:57 |